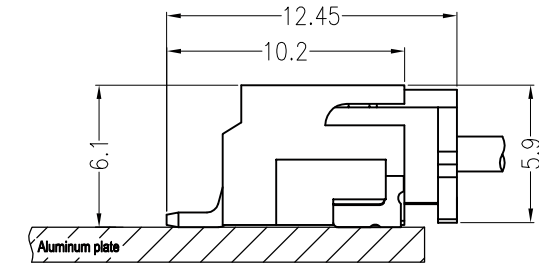
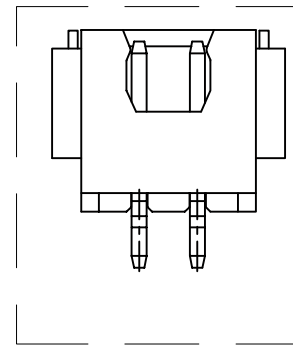
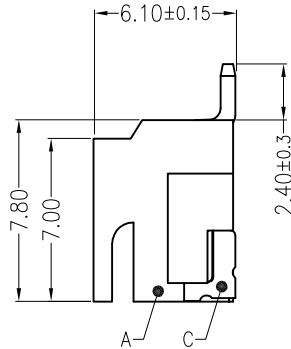
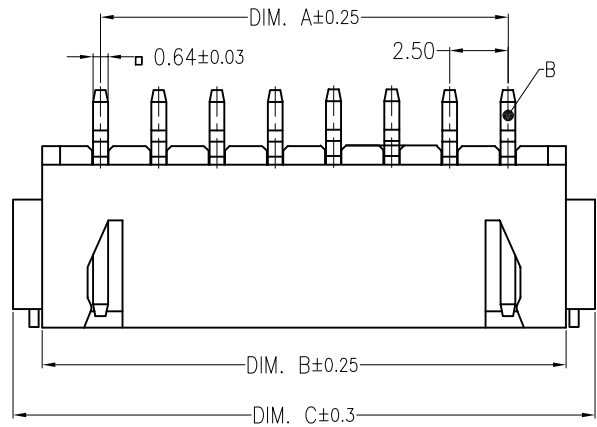


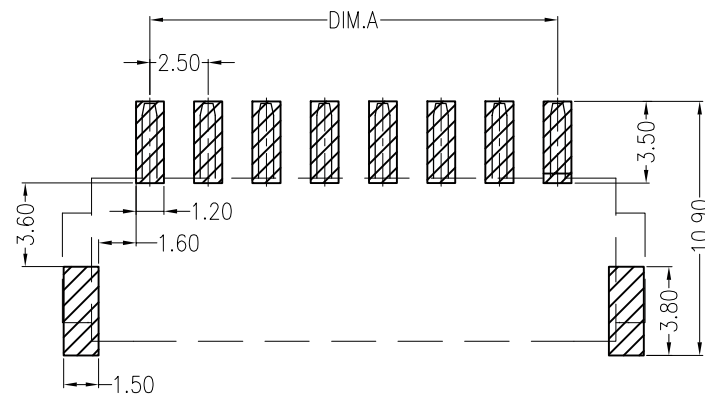
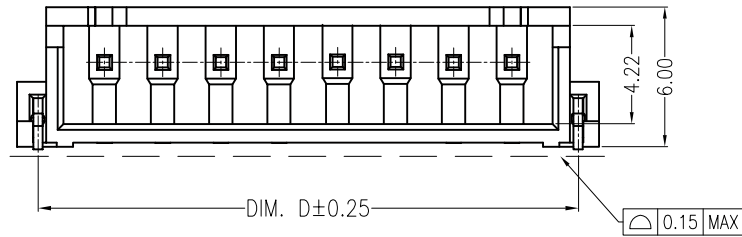
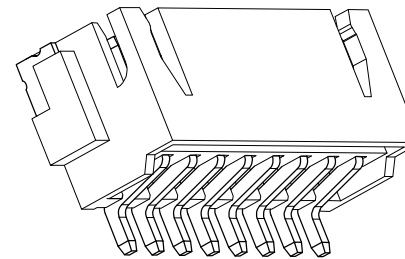
REV	ECN No.	DESCRIPTION	DESIGN	DATE
A	-	NEW RELEASE	吴丹平	2015.05.09
-	-	-	-	-



Assembly Layout

**主要技术参数 Main Specifications**

- 线数 (Poles): 02 to 16
- 接触电阻 (Contact resistance):  $\leq 20m\Omega$
- 绝缘电阻 (Insulation resistance):  $\geq 1000M\Omega$
- 额定电压 (Rated voltage): 250V AC DC
- 额定电流 (Rated current): 3.0A AC DC
- 耐电压 (Withstand Voltage): 1000V AC/minute
- 温度范围 (Temperature Range):  $-25^{\circ}C \sim +105^{\circ}C$



**Board Layout**  
General Tolerance:  $\pm 0.05$

Circuit	Dimensions (mm)			
	DIM. A	DIM. B	DIM. C	DIM. D
02	2.50	7.50	10.00	8.20
03	5.00	10.00	12.50	10.70
04	7.50	12.50	15.00	13.20
05	10.00	15.00	17.50	15.70
06	12.50	17.50	20.00	18.20
07	15.00	20.00	22.50	20.70
08	17.50	22.50	25.00	23.20
09	20.00	25.00	27.50	25.70
10	22.50	27.50	30.00	28.20
11	25.00	30.00	32.50	30.70
12	27.50	32.50	35.00	33.20
13	30.00	35.00	37.50	35.70
14	32.50	37.50	40.00	38.20
15	35.00	40.00	42.50	40.70
16	37.50	42.50	45.00	43.20

ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
C	Solder Tab	2 PCS	Brass	Tin-plated
B	Contacts	2~16 PCS	Brass	Tin-plated
A	HOUSING	1 PCS	LCP	UL 94V-0, COLOR:BEIGE

LEDsconn				TITLE: - 2.5mmPITCH 90°WAFER SMT TYPE	
X.±0.2	X.±0.5'	USE:	MANUFACTURE		
.X±0.10	.X±0.3'	APPD:	邵敬和		
.XX±0.05	.XX±0.2'	CHKD:	田峰		
--	--	DR:	吴丹平		
UNITS: mm		SCALE	SHEET		
		1 : 1	1 / 1		